

EddyCus[®] TF map 5050RM – Resistivity Imaging Device

P_T_5050RM_21



Highlights

- ▶ Electrical integrity imaging
- ▶ High resolution imaging (25 to 1,000,000 points)
- ▶ Defect imaging
- ▶ Mapping of encapsulated layers

Applications

- ▶ Wafer resistivity imaging
- ▶ Ingot and boule resistivity imaging
- ▶ Sputter target composition imaging
- ▶ Purity assessment
- ▶ Electrical discharge machining
- ▶ Material sorting (map: homogeneity assessment)
- ▶ Melting, casting, sintering
- ▶ Defect imaging and integrity assessment

Device Series

- ▶ Metal thickness (nm, μm)
- ▶ Sheet resistance (Ohm/sq)
- ▶ Emissivity
- ▶ Conductivity / resistivity (mOhm cm)
- ▶ Electrical anisotropy (%)
- ▶ Weight (g/m^2) and drying status (%)
- ▶ Permeability (H/m) *Beta*

Materials


- ▶ Semiconductors
 - ▶ Si (mono, poly)
 - ▶ SiC, SiSiC
 - ▶ GaAs
 - ▶ GaN
- ▶ Alloys
- ▶ Metals
- ▶ Graphite
- ▶ Graphene
- ▶ Compounds
- ▶ Composites

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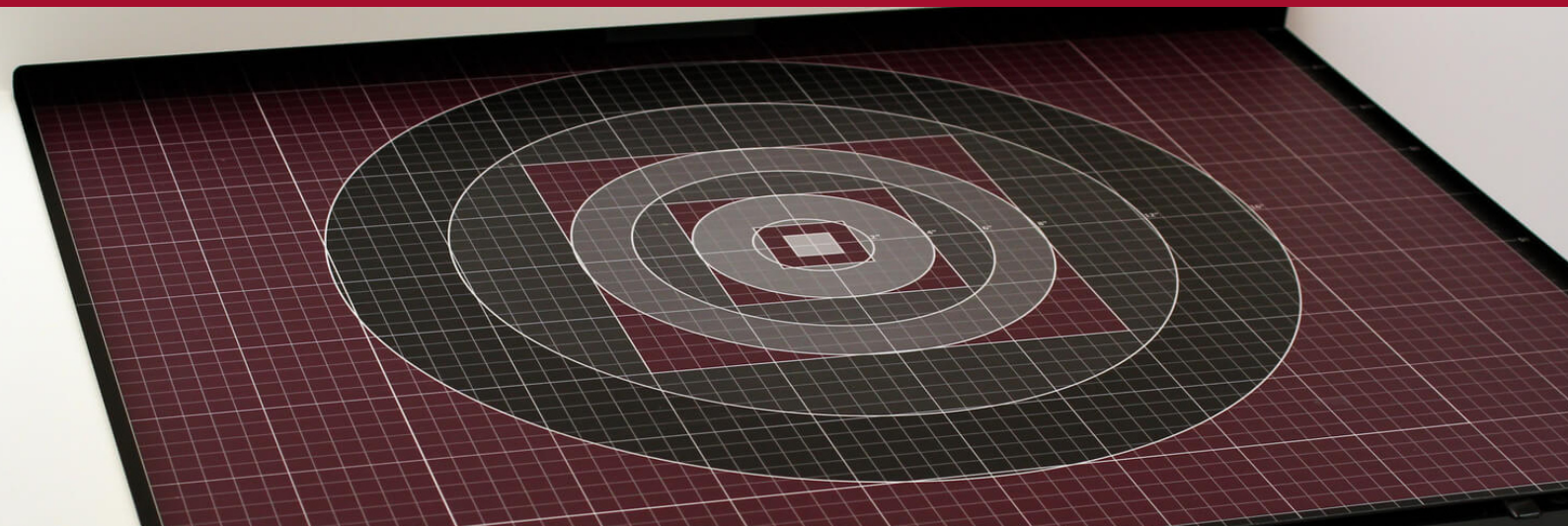
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www.suragus.com/calculator
www.suragus.com/EddyCusMap5050

Engineered and Made in Germany 





Measurement technology	High frequency eddy current sensor
Substrates	Flat, slightly curved
Materials	Wafer, boules, pucks, plates, thin film
Max. scanning area	20 inch / 500 mm x 500 mm x 10 mm
Edge effect correction / exclusion	2 – 10 mm (depending on size, range, setup and requirements)
Max. sample thickness / sensor gap	3 / 5 / 10 / 25 mm (defined by the thickest sample)
Resistivity range	0.002 – 0.1 mOhm cm 0.1 – 100 mOhm cm
accuracy can be optimized within a customer specified range	100 – 1,000 mOhm cm
Scanning pitch	1 / 2 / 5 / 10 mm (other upon request)
Measurement points per time (square shaped samples)	100 measurement points in 5 minutes 10,000 measurement points in 5 minutes
Scanning time	8 inch / 200 mm x 200 mm in 0.5 to 5 minutes (1 – 10 mm pitch) 12 inch / 300 mm x 300 mm in 1.5 to 15 minutes (1 – 10 mm pitch)
Device dimensions (w/h/d) / weight	46.5" x 11.4" x 35.4" / 1,180 mm x 290 mm x 900 mm / 120 kg
Further available features	Metal thickness imaging, anisotropy and sheet resistance sensor

Device Control and Software

- ▶ Pre-defined measurement and product recipes (sizes, pitches, thresholds)
- ▶ Line scan, histogram and area analysis
- ▶ Black and colored image coding
- ▶ Csv & pdf export
- ▶ SPC summary and export
- ▶ 3 user levels
- ▶ Material database for parameter conversion
- ▶ Edge effect compensation
- ▶ Storage and import of data
- ▶ Export of data sets (e.g. to EddyEva, MS Excel, Origin)

